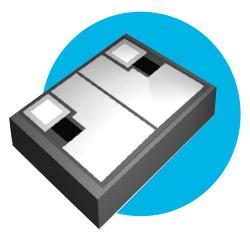
## **Resistors**



# Wire Bondable **Resistor/Capacitor Circuits**

#### **WBC-RC Series**

- Integrated resistor and capacitor
- Proven IRC TaNSil® technology
- 3 types AC Terminator, Tapped and T-Filter





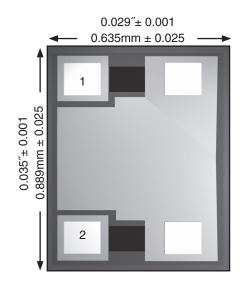
All parts are Pb-free and comply with EU Directive 2011/65/EU (RoHS2)

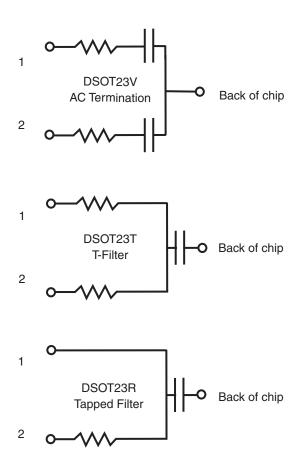
#### **Electrical Data**

				1		
Resistance Value		47Ω	100			
Capacitance Value		47pF	80pF	47pF		
Absolute Tolerance	Resistance		±10%			
	Capacitance		±20%			
Absolute TCR	Resistance	±	±150ppm/°C			
	Capacitance	±	±200ppm/°C			
Package Power Rating			250mW			
Resistor Element Power Rating			125mW			
Capacitor Breakdown Voltage			25V			
Operating Temperature		-55	-55°C to +125°C			
Resistor Noise			<-25dB			
Substrate Material			Silicon			
Substrate Thickness			0.010″ ±0.001 (0.254mm ±0.025)			
Bond Pad Metallization		Aluminu	Aluminum: 10KÅ minimum			
Backside		3KÅ	3KÅ Gold minimum			
Passivation		Silicon Dio	Silicon Dioxide or Silicon Nitride			

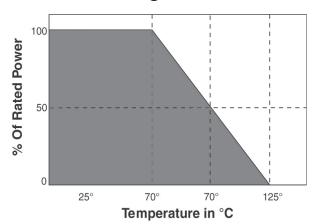


## Physical and Schematic Data





## **Power Derating Data**



**WBC-RC Series** 



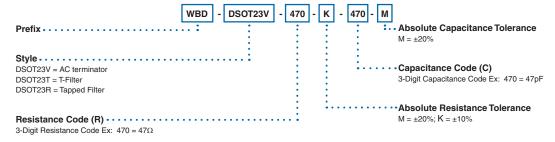
#### **Environmental Data (Resistor)**

Test	Method	Max ∆R	Typical ∆R
Thermal Shock	MIL-STD-202 Method 107 Test condition F	±0.1%	±0.02%
High Temperature Exposure	MIL-STD-883 Method 1008 150°C, 1000 hours	±0.1%	±0.05%
Low Temperature Storage	-55°C, 1000 hours	±0.03%	±0.01%
Life	MIL-STD-202 Method 108 70°C, 1000 hours	±0.5%	±0.01%
Life at Elevated Temperature	MIL-STD-202 Method 108 125°C, 1000 hours	±0.5%	±0.05%

#### **Environmental Data (Capacitor)**

Test	Method	Max ∆C	
Thermal Shock	MIL-STD-202 Method 107 Test condition F	±0.25% + 0.25pF max	
Moisture Resistance	MIL-STD-202 Method 106	±1.0% + 0.25pF max	
Short Time Overload	+25°C, 5 seconds 1.5 X rated voltage	±0.25% + 0.25pF max	
Life at Elevated Temperature	MIL-STD-202 Method 108 125°C, 1000 hours	±0.25% + 0.25pF max	
High Temperature Exposure	100 hours @ 150°C ambient	±0.25% + 0.25pF max	

#### **Ordering Data**



Packaging
Standard packaging is 2" x 2" chip tray. For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.